



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

μP-PROGRAMMABLE PRECISION CLOCK MULTIPLIER

Features

- Not recommended for new designs. For alternatives, see the Si533x family of products.
- Generates frequencies from 2 kHz to 945 MHz and select frequencies to 1.4 GHz from an input frequency of 10 to 710 MHz
- Low jitter clock outputs with jitter generation as low as 0.5 ps rms (12 kHz–20 MHz)
- Integrated loop filter with selectable loop bandwidth (150 kHz to 2 MHz)
- Dual clock inputs w/manual or automatically controlled switching
- Dual clock outputs with selectable signal format (LVPECL, LVDS, CML, CMOS)
- Support for ITU G.709 and custom FEC ratios (255/238, 255/237, 255/236)
- LOS, FOS alarm outputs
- I²C or SPI programmable
- On-chip voltage regulator for 1.8 ±5%, 2.5 or 3.3 V ±10% operation
- Small size: 6 x 6 mm 36-lead QFN
- Pb-free, ROHS compliant

Applications

- SONET/SDH OC-48/STM-16 and OC-192/STM-64 line cards
- GbE/10GbE, 1/2/4/8/10GFC line cards
- ITU G.709 and custom FEC line cards
- Optical modules
- Wireless basestations
- Data converter clocking
- xDSL
- SONET/SDH + PDH clock synthesis
- Test and measurement

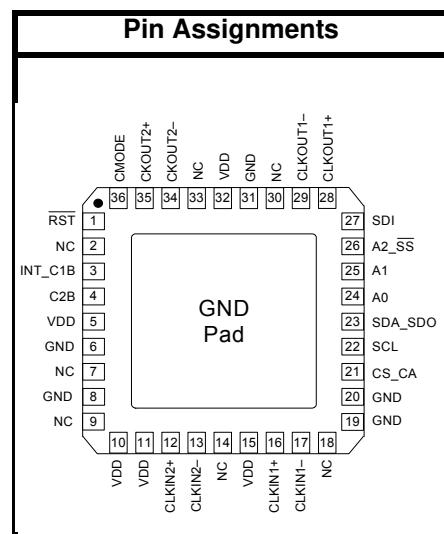
Description

The Si5325 is a low jitter, precision clock multiplier for applications requiring clock multiplication without jitter attenuation. The Si5325 accepts dual clock inputs ranging from 10 to 710 MHz and generates two clock outputs ranging from 2 kHz to 945 MHz and select frequencies to 1.4 GHz. The two outputs are divided down separately from a common source. The device provides frequency translation combinations across this operating range. The Si5325 input clock frequency and clock multiplication ratio are programmable through an I²C or SPI interface. The Si5325 is based on Silicon Laboratories' 3rd-generation DSPLL® technology, which provides frequency synthesis in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The DSPLL loop bandwidth is digitally programmable. Operating from a single 1.8, 2.5, or 3.3 V supply, the Si5325 is ideal for providing clock multiplication in high performance timing applications.



Ordering Information:

See page 56.



Si5325

Functional Block Diagram

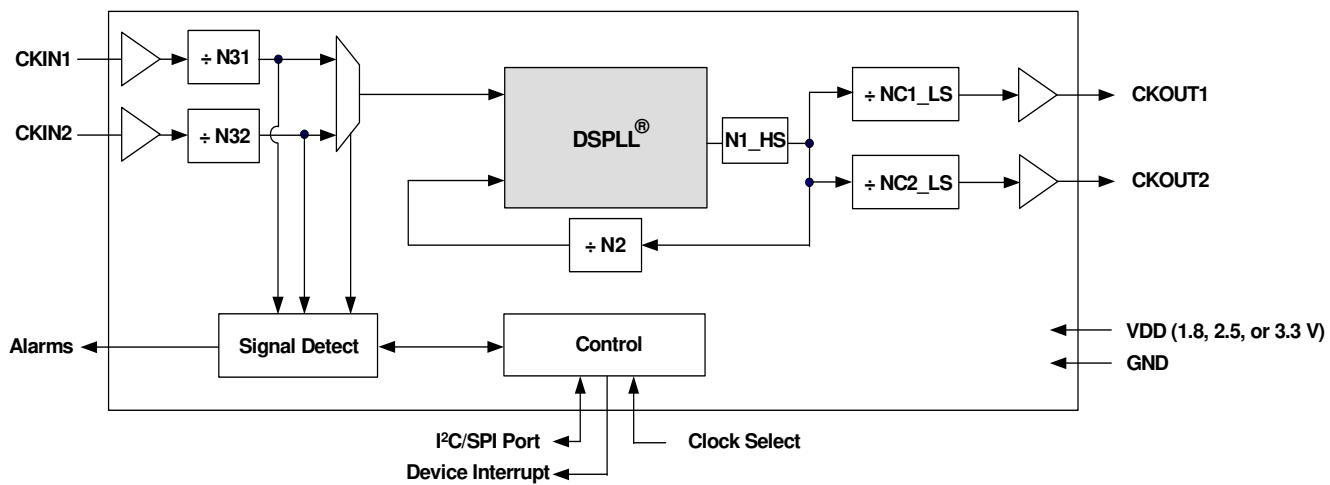


TABLE OF CONTENTS

Section	Page
1. Electrical Specifications	4
2. Functional Description	16
2.1. Further Documentation	16
3. Register Map	17
4. Register Descriptions	19
5. Pin Descriptions: Si5325	52
6. Ordering Guide	56
7. Package Outline: 36-Pin QFN	57
8. Land Pattern: 36-Pin QFN	58
9. Top Marking	60
9.1. Si5325 Top Marking (QFN)	60
9.2. Top Marking Explanation	60
Document Change List	61
Contact Information	62

1. Electrical Specifications

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Ambient Temperature	T _A		-40	25	85	°C
Supply Voltage during Normal Operation	V _{DD}	3.3 V Nominal	2.97	3.3	3.63	V
		2.5 V Nominal	2.25	2.5	2.75	V
		1.8 V Nominal	1.71	1.8	1.89	V

Note: All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions. Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise stated.

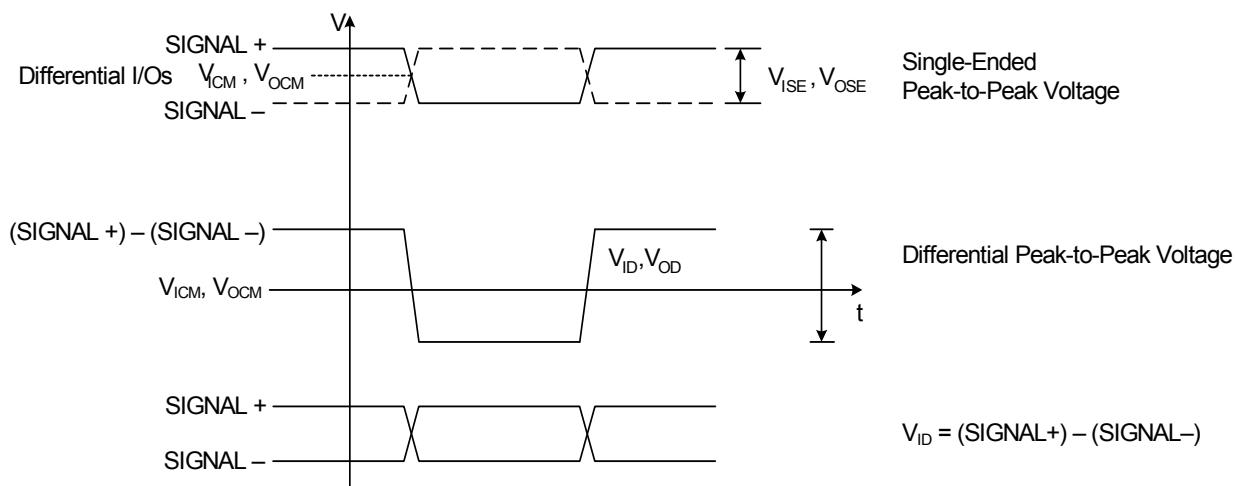


Figure 1. Differential Voltage Characteristics

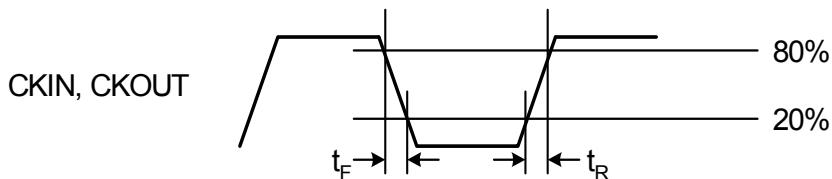


Figure 2. Rise/Fall Time Characteristics

Table 2. DC Characteristics(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit	
Supply Current ¹	I _{DD}	LVPECL Format 622.08 MHz Out Both CKOUTs Enabled	—	251	279	mA	
		LVPECL Format 622.08 MHz Out 1 CKOUT Enabled	—	217	243	mA	
		CMOS Format 19.44 MHz Out Both CKOUTs Enabled	—	204	234	mA	
		CMOS Format 19.44 MHz Out 1 CKOUT Enabled	—	194	220	mA	
		Disable Mode	—	165	—	mA	
CKINn Input Pins²							
Input Common Mode Voltage (Input Threshold Voltage)	V _{ICM}	1.8 V ± 5%	0.9	—	1.4	V	
		2.5 V ± 10%	1	—	1.7	V	
		3.3 V ± 10%	1.1	—	1.95	V	
Input Resistance	CKN _{RIN}	Single-ended	20	40	60	kΩ	
Single-Ended Input Voltage Swing (See Absolute Specs)	V _{ISE}	f _{CKIN} < 212.5 MHz See Figure 1.	0.2	—	—	V _{PP}	
		f _{CKIN} > 212.5 MHz See Figure 1.	0.25	—	—	V _{PP}	
Differential Input Voltage Swing (See Absolute Specs)	V _{ID}	f _{CKIN} < 212.5 MHz See Figure 1.	0.2	—	—	V _{PP}	
		f _{CKIN} > 212.5 MHz See Figure 1.	0.25	—	—	V _{PP}	
Notes:							
<ol style="list-style-type: none"> 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL outputs require nominal V_{DD} ≥ 2.5 V. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details. 5. LVPECL, CML, LVDS and low-swing LVDS measured with F_O = 622.08 MHz. 							

Table 2. DC Characteristics (Continued)(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Clocks (CKOUTn)³						
Common Mode	CKO _{VCM}	LVPECL 100 Ω load line-to-line	V _{DD} -1.42	—	V _{DD} -1.25	V
Differential Output Swing ⁵	CKO _{VD}	LVPECL 100 Ω load line-to-line	1.1	—	1.9	V _{PP}
Single-Ended Output Swing ⁵	CKO _{VSE}	LVPECL 100 Ω load line-to-line	0.5	—	0.93	V _{PP}
Differential Output Voltage	CKO _{VD}	CML 100 Ω load line-to-line	350	425	500	mV _{PP}
Common Mode Output Voltage	CKO _{VCM}	CML 100 Ω load line-to-line	—	V _{DD} -0.36	—	V
Differential Output Voltage	CKO _{VD}	LVDS 100 Ω load line-to-line	500	700	900	mV _{PP}
		Low Swing LVDS 100 Ω load line-to-line	350	425	500	mV _{PP}
Common Mode Output Voltage	CKO _{VCM}	LVDS 100 Ω load line-to-line	1.125	1.2	1.275	V
Differential Output Resistance	CKO _{RD}	CML, LVPECL, LVDS	—	200	—	Ω
Output Voltage Low	CKO _{VOLLH}	CMOS	—	—	0.4	V
Output Voltage High	CKO _{VOHLH}	V _{DD} = 1.71 V CMOS	0.8 x V _{DD}	—	—	V
Notes:						
<ol style="list-style-type: none"> 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL outputs require nominal VDD ≥ 2.5 V. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details. 5. LVPECL, CML, LVDS and low-swing LVDS measured with F_o = 622.08 MHz. 						

Table 2. DC Characteristics (Continued)(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit	
Output Drive Current (CMOS driving into CKO _{VOL} for output low or CKO _{VOH} for output high. CKOUT+ and CKOUT– shorted externally)	CKO _{IO}	ICMOS[1:0] =11 V _{DD} = 1.8 V	—	7.5	—	mA	
		ICMOS[1:0] =10 V _{DD} = 1.8 V	—	5.5	—	mA	
		ICMOS[1:0] =01 V _{DD} = 1.8 V	—	3.5	—	mA	
		ICMOS[1:0] =00 V _{DD} = 1.8 V	—	1.75	—	mA	
		ICMOS[1:0] =11 V _{DD} = 3.3 V	—	32	—	mA	
		ICMOS[1:0] =10 V _{DD} = 3.3 V	—	24	—	mA	
		ICMOS[1:0] =01 V _{DD} = 3.3 V	—	16	—	mA	
		ICMOS[1:0] =00 V _{DD} = 3.3 V	—	8	—	mA	
2-Level LVCMOS Input Pins							
Input Voltage Low	V _{IL}	V _{DD} = 1.71 V	—	—	0.5	V	
		V _{DD} = 2.25 V	—	—	0.7	V	
		V _{DD} = 2.97 V	—	—	0.8	V	
Input Voltage High	V _{IH}	V _{DD} = 1.89 V	1.4	—	—	V	
		V _{DD} = 2.25 V	1.8	—	—	V	
		V _{DD} = 3.63 V	2.5	—	—	V	
Notes:							
<ol style="list-style-type: none"> 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL outputs require nominal VDD ≥ 2.5 V. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details. 5. LVPECL, CML, LVDS and low-swing LVDS measured with F_O = 622.08 MHz. 							

Table 2. DC Characteristics (Continued)

($V_{DD} = 1.8 \pm 5\%$, $2.5 \pm 10\%$, or $3.3 V \pm 10\%$, $T_A = -40$ to $85^\circ C$)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
3-Level Input Pins⁴						
Input Voltage Low	V_{ILL}		—	—	$0.15 \times V_{DD}$	V
Input Voltage Mid	V_{IMM}		$0.45 \times V_{DD}$	—	$0.55 \times V_{DD}$	V
Input Voltage High	V_{IHH}		$0.85 \times V_{DD}$	—	—	V
Input Low Current	I_{ILL}	See Note 4	-20	—	—	μA
Input Mid Current	I_{IMM}	See Note 4	-2	—	+2	μA
Input High Current	I_{IHH}	See Note 4	—	—	20	μA
LVC MOS Output Pins						
Output Voltage Low	V_{OL}	$IO = 2 \text{ mA}$ $V_{DD} = 1.71 \text{ V}$	—	—	0.4	V
Output Voltage Low		$IO = 2 \text{ mA}$ $V_{DD} = 2.97 \text{ V}$	—	—	0.4	V
Output Voltage High	V_{OH}	$IO = -2 \text{ mA}$ $V_{DD} = 1.71 \text{ V}$	$V_{DD} - 0.4$	—	—	V
Output Voltage High		$IO = -2 \text{ mA}$ $V_{DD} = 2.97 \text{ V}$	$V_{DD} - 0.4$	—	—	V
Disabled Leakage Current	I_{OZ}	$RSTb = 0$	-100	—	100	μA
Notes:						
<ol style="list-style-type: none"> 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL outputs require nominal $VDD \geq 2.5 \text{ V}$. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details. 5. LVPECL, CML, LVDS and low-swing LVDS measured with $Fo = 622.08 \text{ MHz}$. 						

Table 3. AC Characteristics(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
CKINn Input Pins						
Input Frequency	CKN _F		10	—	710	MHz
Input Duty Cycle (Minimum Pulse Width)	CKN _{DC}	Whichever is smaller (i.e., the 40% / 60% limitation applies only to high frequency clocks)	40	—	60	%
			2	—	—	ns
Input Capacitance	CKN _{CIN}		—	—	3	pF
Input Rise/Fall Time	CKN _{TRF}	20–80% See Figure 2	—	—	11	ns
CKOUTn Output Pins						
(See ordering section for speed grade vs frequency limits)						
Output Frequency (Output not configured for CMOS or Disabled)	CKO _F	N1 ≥ 6	0.002	—	945	MHz
		N1 = 5	970	—	1134	MHz
		N1 = 4	1.213	—	1.4	GHz
Maximum Output Frequency in CMOS Format	CKO _F		—	—	212.5	MHz
Output Rise/Fall (20–80 %) @ 622.08 MHz output	CKO _{TRF}	Output not configured for CMOS or Disabled See Figure 2	—	230	350	ps
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO _{TRF}	CMOS Output V _{DD} = 1.71 C _{LOAD} = 5 pF	—	—	8	ns
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO _{TRF}	CMOS Output V _{DD} = 2.97 C _{LOAD} = 5 pF	—	—	2	ns
Output Duty Cycle Uncertainty @ 622.08 MHz	CKO _{DC}	100 Ω Load Line-to-Line Measured at 50% Point (Not for CMOS)	—	—	+/-40	ps

Si5325

Table 3. AC Characteristics (Continued)

($V_{DD} = 1.8 \pm 5\%$, $2.5 \pm 10\%$, or $3.3 V \pm 10\%$, $T_A = -40$ to $85^\circ C$)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
LVC MOS Input Pins						
Minimum Reset Pulse Width	t_{RSTMN}		1	—	—	μs
Reset to Microprocessor Access Ready	t_{READY}		—	—	10	ms
Input Capacitance	C_{in}		—	—	3	pF
LVC MOS Output Pins						
Rise/Fall Times	t_{RF}	$C_{LOAD} = 20 pF$ See Figure 2	—	25	—	ns
LOSn Trigger Window	LOS_{TRIG}	From last $CKIN_n \uparrow$ to \downarrow Internal detection of LOSn $N_3 \neq 1$	—	—	4.5 x N3	T_{CKIN}
Time to Clear LOL after LOS Cleared	t_{CLRLOL}	$\downarrow LOS$ to $\downarrow LOL$ Fold = Fnew Stable Xa/XB reference	—	10	—	ms
Device Skew						
Output Clock Skew	t_{SKEW}	\uparrow of $CKOUT_n$ to \uparrow of $CKOUT_m$, $CKOUT_n$ and $CKOUT_m$ at same frequency and signal format <u>PHASEOFFSET</u> = 0 <u>CKOUT_ALWAYS_ON</u> = 1 <u>SQ_ICAL</u> = 1	—	—	100	ps
Phase Change due to Temperature Variation	t_{TEMP}	Max phase changes from −40 to +85 °C	—	300	500	ps

Table 3. AC Characteristics (Continued)(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
PLL Performance						
(fin = fout = 622.08 MHz; BW = 120 Hz; LVPECL)						
Lock Time	t _{LOCKMP}	Start of ICAL to ↓ of LOL	—	35	1200	ms
Closed Loop Jitter Peaking	J _{PK}		—	0.05	0.1	dB
Jitter Tolerance	J _{TOL}	Jitter Frequency ≥ Loop Bandwidth	5000/BW	—	—	ns pk-pk
Phase Noise fout = 622.08 MHz	CKO _{PN}	1 kHz Offset	—	–90	—	dBc/Hz
		10 kHz Offset	—	–113	—	dBc/Hz
		100 kHz Offset	—	–118	—	dBc/Hz
		1 MHz Offset	—	–132	—	dBc/Hz
Subharmonic Noise	SP _{SUBH}	Phase Noise @ 100 kHz Offset	—	–88	—	dBc
Spurious Noise	SP _{SPUR}	Max spur @ n × F3 (n ≥ 1, n × F3 < 100 MHz)	—	–93	—	dBc

Table 4. Microprocessor Control(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
I²C Bus Lines (SDA, SCL)						
Input Voltage Low	V _{IL} _{I2C}		—	—	0.25 × V _{DD}	V
Input Voltage High	V _{IH} _{I2C}		0.7 × V _{DD}	—	V _{DD}	V
Hysteresis of Schmitt trigger inputs	VHYS _{I2C}	V _{DD} = 1.8V	0.1 × V _{DD}	—	—	V
		V _{DD} = 2.5 or 3.3 V	0.05 × V _{DD}	—	—	V
Output Voltage Low	VOL _{I2C}	V _{DD} = 1.8 V IO = 3 mA	—	—	0.2 × V _{DD}	V
		V _{DD} = 2.5 or 3.3 V IO = 3 mA	—	—	0.4	V

Si5325

Table 4. Microprocessor Control (Continued)

($V_{DD} = 1.8 \pm 5\%$, $2.5 \pm 10\%$, or $3.3 V \pm 10\%$, $T_A = -40$ to $85^\circ C$)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SPI Specifications						
Duty Cycle, SCLK	t_{DC}	SCLK = 10 MHz	40	—	60	%
Cycle Time, SCLK	t_c		100	—	—	ns
Rise Time, SCLK	t_r	20–80%	—	—	25	ns
Fall Time, SCLK	t_f	20–80%	—	—	25	ns
Low Time, SCLK	t_{lsc}	20–20%	30	—	—	ns
High Time, SCLK	t_{hsc}	80–80%	30	—	—	ns
Delay Time, SCLK Fall to SDO Active	t_{d1}		—	—	25	ns
Delay Time, SCLK Fall to SDO Transition	t_{d2}		—	—	25	ns
Delay Time, SS Rise to SDO Tri-state	t_{d3}		—	—	25	ns
Setup Time, SS to SCLK Fall	t_{su1}		25	—	—	ns
Hold Time, SS to SCLK Rise	t_{h1}		20	—	—	ns
Setup Time, SDI to SCLK Rise	t_{su2}		25	—	—	ns
Hold Time, SDI to SCLK Rise	t_{h2}		20	—	—	ns
Delay Time between Slave Selects	t_{cs}		25	—	—	ns

Table 5. Jitter Generation

Parameter	Symbol	Test Condition*	Min	Typ	Max	Unit
		Measurement Filter				
Jitter Gen OC-192	JGEN	0.02–80 MHz	—	.49	—	ps _{rms}
		4–80 MHz	—	.23	—	ps _{rms}
		0.05–80 MHz	—	.47	—	ps _{rms}
Jitter Gen OC-48	JGEN	0.12–20 MHz	—	.48	—	ps _{rms}

*Note: Test conditions:

1. f_{IN} = f_{OUT} = 622.08 MHz
2. Clock input: LVPECL
3. Clock output: LVPECL
4. PLL bandwidth: 877 kHz
5. V_{DD} = 2.5 V
6. T_A = 85 °C

Table 6. Thermal Characteristics(V_{DD} = 1.8 ±5%, 2.5 ±10%, or 3.3 V ±10%, T_A = –40 to 85 °C)

Parameter	Symbol	Test Condition	Value	Unit
Thermal Resistance Junction to Ambient	θ _{JA}	Still Air	32	°C/W
Thermal Resistance Junction to Case	θ _{JC}	Still Air	14	°C/W

Table 7. Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
DC Supply Voltage	V _{DD}	–0.5 to 3.8	V
LVCMOS Input Voltage	V _{DIG}	–0.3 to (V _{DD} + 0.3)	V
CKINn Voltage Level Limits	CKN _{VIN}	0 to V _{DD}	V
XA/XB Voltage Level Limits	X _A _{VIN}	0 to 1.2	V
Operating Junction Temperature	T _{JCT}	–55 to 150	C
Storage Temperature Range	T _{STG}	–55 to 150	C
ESD HBM Tolerance (100 pF, 1.5 kΩ); All pins except CKIN+/CKIN–		2	kV
ESD MM Tolerance; All pins except CKIN+/CKIN–		150	V
ESD HBM Tolerance (100 pF, 1.5 kΩ); CKIN+/CKIN–		750	V
ESD MM Tolerance; CKIN+/CKIN–		100	V
Latch-Up Tolerance		JESD78 Compliant	
Note:	Permanent device damage may occur if the Absolute Maximum Ratings are exceeded. Functional operation should be restricted to the conditions as specified in the operation sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.		

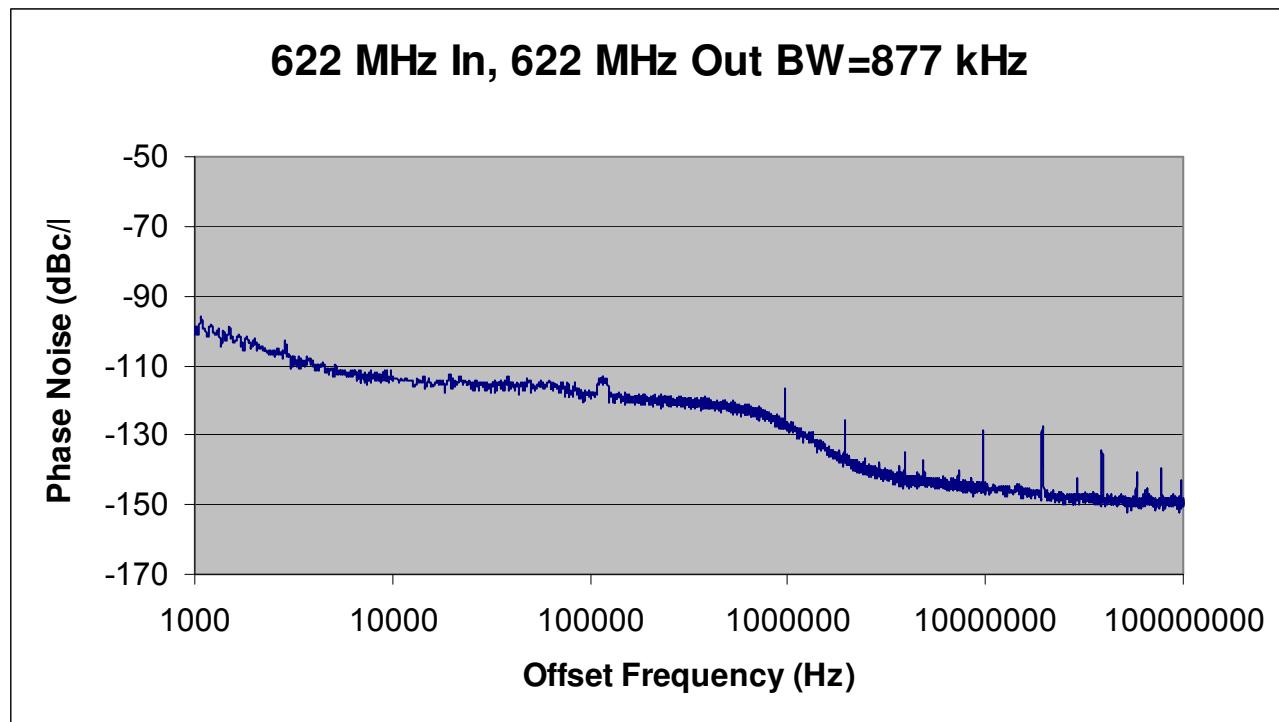


Figure 3. Typical Phase Noise Plot

Table 8. Typical RMS Jitter Values

Jitter Bandwidth	RMS Jitter (fs)
OC-48, 12 kHz to 20 MHz	374
OC-192, 20 kHz to 80 MHz	388
OC-192, 4 MHz to 80 MHz	181
OC-192, 50 kHz to 80 MHz	377
Broadband, 800 Hz to 80 MHz	420

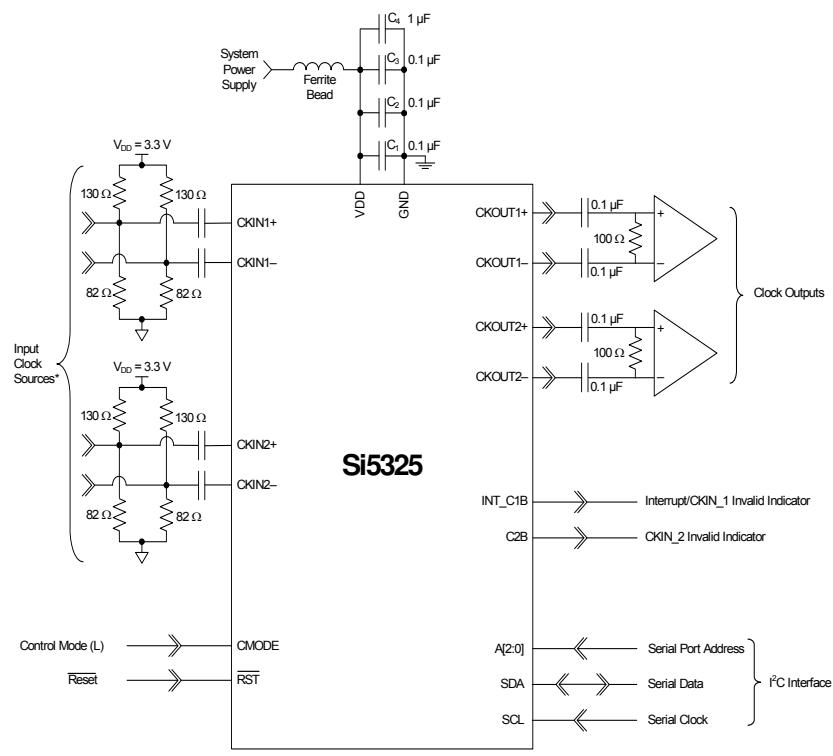


Figure 4. Si5325 Typical Application Circuit (I²C Control Mode)

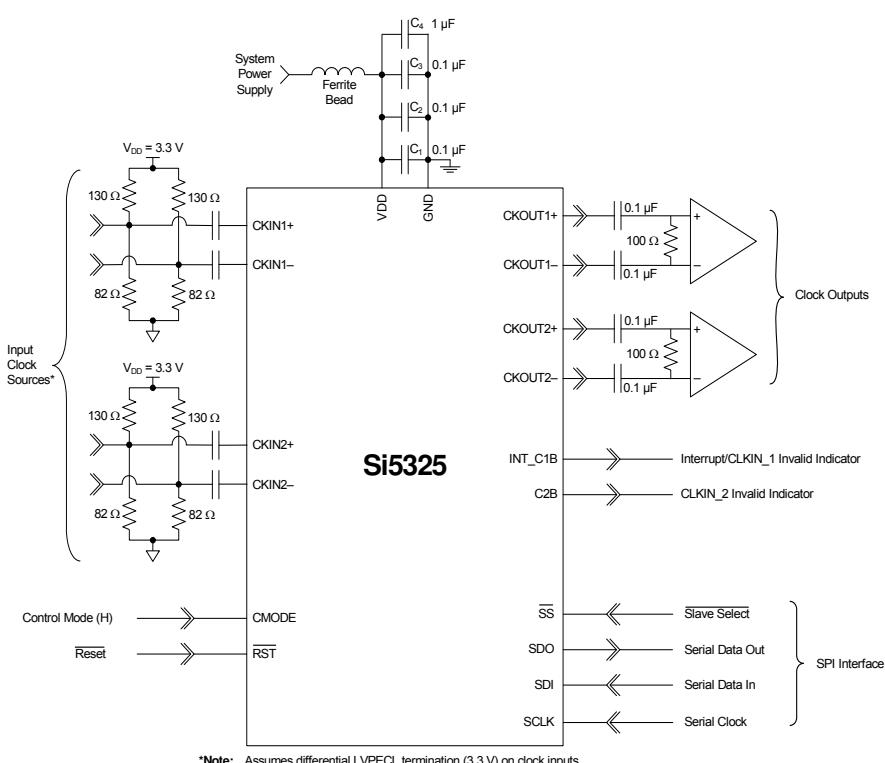


Figure 5. Si5325 Typical Application Circuit (SPI Control Mode)

2. Functional Description

The Si5325 is a low jitter, precision clock multiplier for applications requiring clock multiplication without jitter attenuation. The Si5325 accepts dual clock inputs ranging from 10 to 710 MHz and generates two synchronous clock outputs ranging from 2 kHz to 945 MHz and select frequencies to 1.4 GHz. The device provides frequency translation across this operating range. Independent dividers are available for each input clock and output clock, so the Si5325 can accept input clocks at different frequencies and it can generate output clocks at different frequencies. The Si5325 input clock frequency and clock multiplication ratio are programmable through an I²C or SPI interface. Silicon Laboratories offers a PC-based software utility, DSPLLsim, that can be used to determine the optimum PLL divider settings for a given input frequency/clock multiplication ratio combination that minimizes phase noise and power consumption. This utility can be downloaded from <http://www.silabs.com/timing> (click on Documentation).

The Si5325 is based on Silicon Laboratories' third-generation DSPLL® technology, which provides frequency synthesis in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The Si5325 PLL loop bandwidth is digitally programmable and supports a range from 150 kHz to 1.3 MHz. The DSPLLsim software utility can be used to calculate valid loop bandwidth settings for a given input clock frequency/clock multiplication ratio.

In the case when the input clocks enter alarm conditions, the PLL will freeze the DCO output frequency near its last value to maintain operation with an internal state close to the last valid operating state.

The Si5325 has two differential clock outputs. The electrical format of each clock output is independently programmable to support LVPECL, LVDS, CML, or CMOS loads. If not required, the second clock output can be powered down to minimize power consumption.

For system-level debugging, a bypass mode is available which drives the output clock directly from the input clock, bypassing the internal DSPLL. The device is powered by a single 1.8, 2.5, or 3.3 V supply.

2.1. Further Documentation

Consult the Silicon Laboratories Any-Frequency Precision Clock Family Reference Manual (FRM) for detailed information about the Si5325. Additional design support is available from Silicon Laboratories through your distributor.

Silicon Laboratories has developed a PC-based software utility called DSPLLsim to simplify device configuration, including frequency planning and loop bandwidth selection. The FRM and this utility can be downloaded from <http://www.silabs.com/timing>; click on Documentation.

3. Register Map

All register bits that are not defined in this map should always be written with the specified Reset Values. The writing to these bits of values other than the specified Reset Values may result in undefined device behavior. Registers not listed, such as Register 64, should never be written to.

Register	D7	D6	D5	D4	D3	D2	D1	D0
0			CKOUT_ALWAYS_ON				BYPASS_REG	
1					CK_PRIOR2[1:0]		CK_PRIOR[1:0]	
2			BWSEL_REG[3:0]					
3		CKSEL_REG[1:0]		SQ_ICAL				
4		AUTOSEL_REG[1:0]						
5		ICMOS[1:0]						
6			SFOUT2_REG[2:0]				SFOUT1_REG[2:0]	
7							FOSREFSEL[2:0]	
8		HLOG_2[1:0]	HLOG_1[1:0]					
10					DSBL2_REG	DSBL1_REG		
11							PD_CK2	PD_CK1
19	FOS_EN		FOS_THR[1:0]		VALTIME[1:0]			
20					CK2_BAD_PIN	CK1_BAD_PIN		INT_PIN
21							CK1_ACTV_PIN	CKSEL_PIN
22					CK_ACTV_POL	CK_BAD_POL		INT_POL
23						LOS2_MSK	LOS1_MSK	
24						FOS2_MSK	FOS1_MSK	
25		N1_HS[2:0]						
31							NC1_LS[19:16]	
32					NC1_LS[15:8]			
33					NC1_LS[7:0]			
34							NC2_LS[19:16]	
35					NC2_LS[15:8]			
36					NC2_LS[7:0]			
40							N2_LS[19:16]	
41					N2_LS[15:8]			
42					N2_LS[7:0]			
43							N31[18:16]	
44					N31[15:8]			
45					N31[7:0]			
46							N32[18:16]	
47					N32[15:8]			
48					N32[7:0]			
55				CLKIN2RATE[2:0]			CLKIN1RATE[2:0]	
128							CK2_ACTV_REG	CK1_ACTV_REG

Si5325

Register	D7	D6	D5	D4	D3	D2	D1	D0
129						LOS2_INT	LOS1_INT	
130						FOS2_INT	FOS1_INT	
131						LOS2_FLG	LOS1_FLG	
132					FOS2_FLG	FOS1_FLG		
134	PARTNUM_RO[11:4]							
135	PARTNUM_RO[3:0]				REVID_RO[3:0]			
136	RST_REG	ICAL						
138							LOS2_EN [1:1]	LOS1_EN [1:1]
139			LOS2_EN[0:0]	LOS1_EN[0:0]			FOS2_EN	FOS1_EN
142	INDEPENDENTSKEW1[7:0]							
143	INDEPENDENTSKEW2[7:0]							

4. Register Descriptions

Register 0.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			CKOUT_ALWAYS_ON				BYPASS_REG	
Type	R	R	R/W	R	R	R	R/W	R

Reset value = 0001 0100

Bit	Name	Function
7:6	Reserved	
5	CKOUT_ALWAYS_ON	CKOUT Always On. This will bypass the SQ_ICAL function. Output will be available even if SQ_ICAL is on and ICAL is not complete or successful. See Table 9 on page 51. 0: Squelch output until part is calibrated (ICAL). 1: Provide an output. Note: The frequency may be significantly off until the part is calibrated.
4:2	Reserved	
1	BYPASS_REG	Bypass Register. This bit enables or disables the PLL bypass mode. Use only when the device is in VCO freeze or before the first ICAL. Bypass mode is not supported for CMOS output clocks. 0: Normal operation 1: Bypass mode. Selected input clock is connected to CKOUT buffers, bypassing PLL. Bypass mode is not supported for CMOS outputs.
0	Reserved	

Si5325

Register 1.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name					CK_PRIOR2 [1:0]	CK_PRIOR1 [1:0]		
Type	R	R	R	R	R/W	R/W		

Reset value = 1110 0100

Bit	Name	Function
7:4	Reserved	
3:2	CK_PRIOR2 [1:0]	CK_PRIOR 2. Selects which of the input clocks will be 2nd priority in the autoselection state machine. 00: CKIN1 is 2nd priority. 01: CKIN2 is 2nd priority. 10: Reserved 11: Reserved
1:0	CK_PRIOR1 [1:0]	CK_PRIOR 1. Selects which of the input clocks will be 1st priority in the autoselection state machine. 00: CKIN1 is 1st priority. 01: CKIN2 is 1st priority. 10: Reserved 11: Reserved

Register 2.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		BWSEL_REG [3:0]						
Type		R/W		R		R	R	R

Reset value = 0100 0010

Bit	Name	Function
7:4	BWSEL_REG [3:0]	BWSEL_REG. Selects nominal f3dB bandwidth for PLL. See the DSPLLsim for settings. After BWSEL_REG is written with a new value, an ICAL is required for the change to take effect.
3:0	Reserved	

Register 3.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	CKSEL_REG [1:0]							
Type	R/W		R	R/W	R	R	R	R

Reset value = 0000 0101

Bit	Name	Function
7:6	CKSEL_REG [1:0]	CKSEL_REG. If the device is operating in register-based manual clock selection mode (AUTOSEL_REG = 00), and CKSEL_PIN = 0, then these bits select which input clock will be the active input clock. If CKSEL_PIN = 1 and AUTOSEL_REG = 00, the CS_CA input pin continues to control clock selection and CKSEL_REG is of no consequence. 00: CKIN_1 selected. 01: CKIN_2 selected. 10: Reserved 11: Reserved
5	Reserved	
4	SQ_ICAL	SQ_ICAL. This bit determines if the output clocks will remain enabled or be squelched (disabled) during an internal calibration. See Table 9 on page 51. 0: Output clocks enabled during ICAL. 1: Output clocks disabled during ICAL.
3:0	Reserved	

Si5325

Register 4.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	AUTOSEL_REG [1:0]							
Type	R/W		R	R	R	R	R	R

Reset value = 0001 0010

Bit	Name	Function
7:6	AUTOSEL_REG [1:0]	AUTOSEL_REG [1:0]. Selects method of input clock selection to be used. 00: Manual (either register or pin controlled, see CKSEL_PIN) 01: Automatic Non-Revertive 10: Automatic Revertive 11: Reserved
5:0	Reserved	

Register 5.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	ICMOS [1:0]							
Type	R/W		R	R	R	R	R	R

Reset value = 1110 1101

Bit	Name	Function
7:6	ICMOS [1:0]	ICMOS [1:0]. When the output buffer is set to CMOS mode, these bits determine the output buffer drive strength. The first number below refers to 3.3 V operation; the second to 1.8 V operation. These values assume CKOUT+ is tied to CKOUT-. 00: 8 mA/2 mA. 01: 16 mA/4 mA 10: 24 mA/6 mA 11: 32 mA/8 mA
5:0	Reserved	

Register 6.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name			SFOUT2_REG [2:0]			SFOUT1_REG [2:0]		
Type	R	R	R/W			R/W		

Reset value = 0010 1101

Bit	Name	Function
7:6	Reserved	
5:3	SFOUT2_REG [2:0]	SFOUT2_REG [2:0]. Controls output signal format and disable for CKOUT2 output buffer. Bypass mode is not supported for CMOS output clocks. 000: Reserved 001: Disable 010: CMOS (Bypass mode is not supported for CMOS outputs) 011: Low swing LVDS 100: Reserved 101: LVPECL 110: CML 111: LVDS
2:0	SFOUT1_REG [2:0]	SFOUT1_REG [2:0]. Controls output signal format and disable for CKOUT1 output buffer. Bypass mode is not supported for CMOS output clocks. 000: Reserved 001: Disable 010: CMOS (Bypass mode is not supported for CMOS outputs) 011: Low swing LVDS 100: Reserved 101: LVPECL 110: CML 111: LVDS

Si5325

Register 7.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	FOSREFSEL [2:0]							
Type	R	R	R	R	R	R/W		

Reset value = 0010 1010

Bit	Name	Function
7:3	Reserved	
2:0	FOSREFSEL [2:0]	FOSREFSEL [2:0]. Selects which input clock is used as the reference frequency for Frequency Off-Set (FOS) alarms. 000: XA/XB (External reference) 001: CKIN1 010: CKIN2 011: Reserved 100: Reserved 101: Reserved 110: Reserved 111: Reserved

Register 8.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name	HLOG_2[1:0]		HLOG_1[1:0]					
Type	R/W		R/W		R	R	R	R

Reset value = 0000 0000

Bit	Name	Function
7:6	HLOG_2 [1:0]	HLOG_2 [1:0]. 00: Normal operation 01: Holds CKOUT2 output at static logic 0. Entrance and exit from this state will occur without glitches or runt pulses. 10:Holds CKOUT2 output at static logic 1. Entrance and exit from this state will occur without glitches or runt pulses. 11: Reserved
5:4		HLOG_1 [1:0]. 00: Normal operation 01: Holds CKOUT1 output at static logic 0. Entrance and exit from this state will occur without glitches or runt pulses. 10: Holds CKOUT1 output at static logic 1. Entrance and exit from this state will occur without glitches or runt pulses. 11: Reserved
3:0	Reserved	